DZ5S068D

Silicon epitaxial planar type

For surge absorption circuits
DZ5J068D in SSMini5 type package

■ Features

- Excellent rising characteristics of zener current I_Z
- Low zener operating resistance R_Z
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Basic Part Number

Dual DZ3X068D (Common anode)

■ Packaging

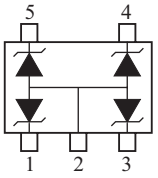
Embossed type (Thermo-compression sealing): 8000 pcs / reel (standard)

■ Package

- Code
  SSMini5-F4-B
- Pin Name
  1: Cathode -1
  2: Anode-1, 2, 3, 4
  3: Cathode -2
  4: Cathode -3
  5: Cathode -4

■ Marking Symbol: 02

■ Internal Connection



■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Total power dissipation *	P_T	150	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	–55 to +150	°C

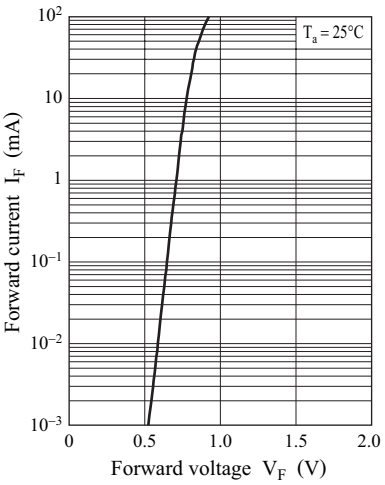
Note) *: P_T = 150 mW achieved with a printed circuit board. (4 diode total)

■ Common Electrical Characteristics $T_a = 25°C \pm 3°C$

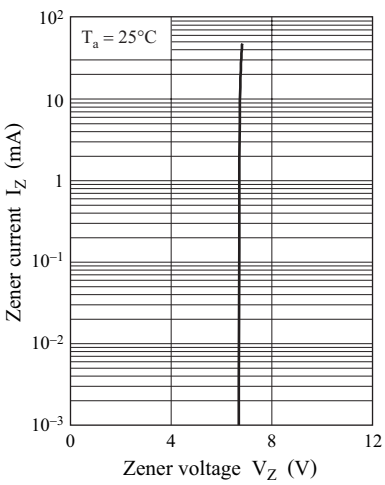
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 10 mA			1.0	V
Zener voltage *	V_Z	I_Z = 5 mA	6.46		7.14	V
Zener operating resistance	R_Z	I_Z = 5 mA			30	Ω
Zener rise operating resistance	R_{ZK}	I_Z = 0.5 mA			60	Ω
Reverse current	I_R	V_R = 4.0 V			0.1	μA
Temparature coefficient of zener voltage	S_Z	I_Z = 5 mA		3.1		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Electrostatic breakdown voltage: ±10 kV
Test method: IEC61000-4-2 (C = 150 pF, R = 330 Ω, Contact discharge: 10 times)
3. *1: The temperature must be controlled 25°C for V_Z measurement. V_Z value measured at other temperature must be adjusted to V_Z (25°C)
*2: V_Z guaranteed 20 ms after current flow.
*3: T_j = 25°C to 150°C

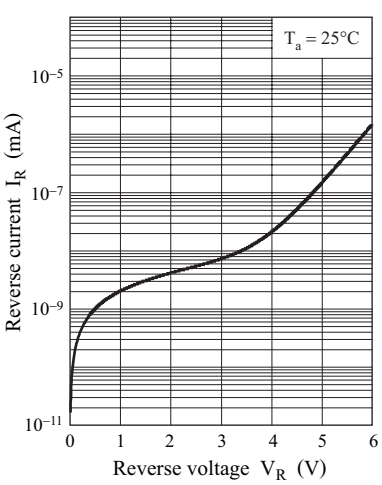
I_F — V_F



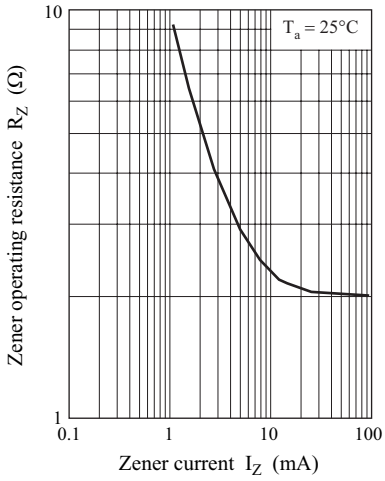
I_Z — V_Z



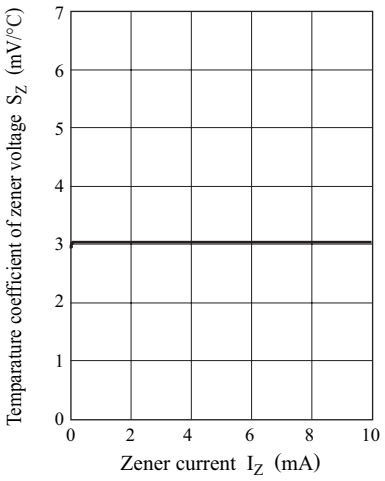
I_R — V_R



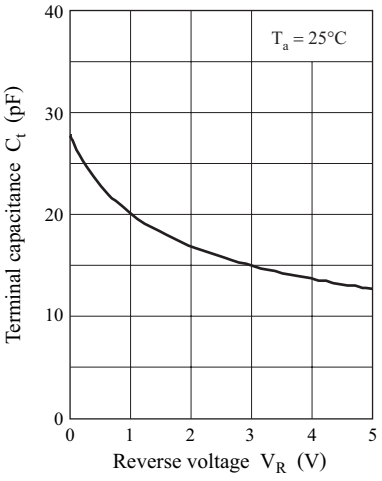
R_Z — I_Z



S_Z — I_Z

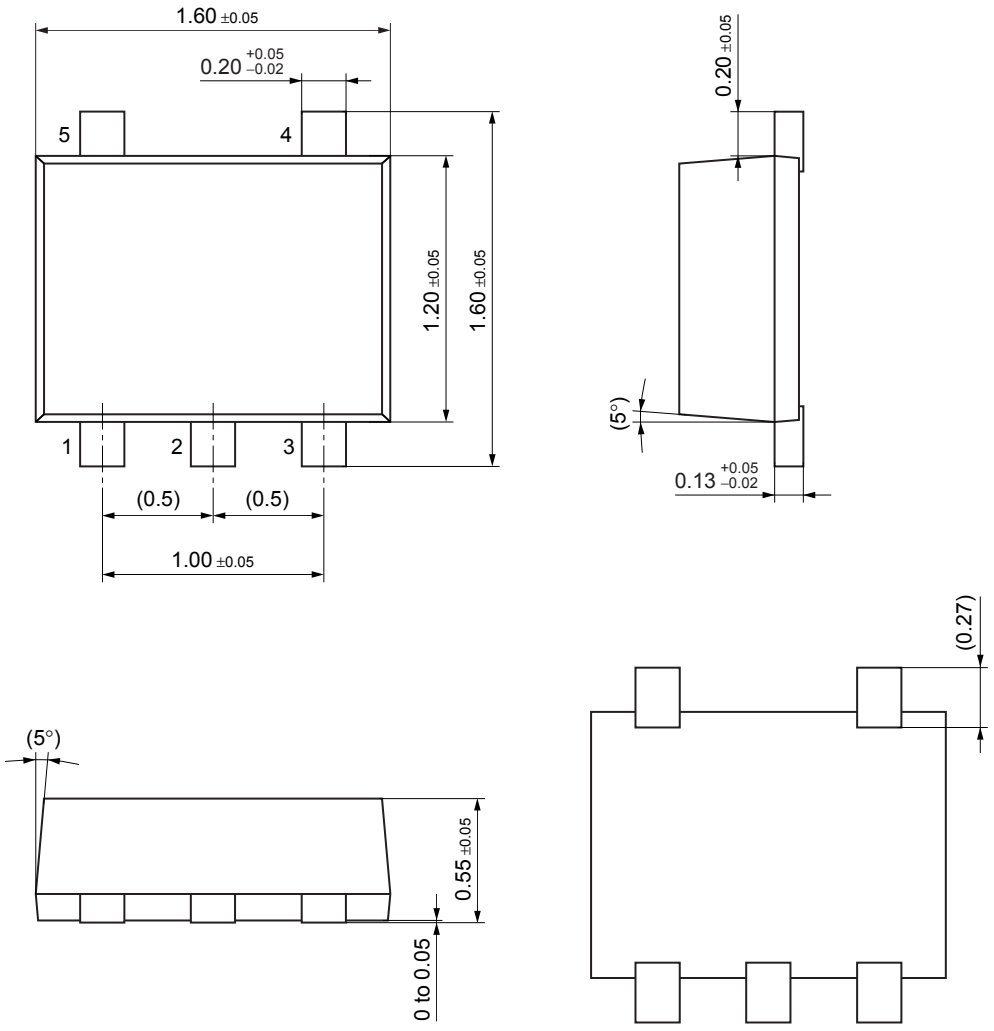


C_t — V_R



SSMini5-F4-B

Unit: mm



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